

	Hits	Search Text	DBs
1	2	((resist or photoresist) same (pattern\$4 or structure)) and (surfactant or (non\$3ionic near3 surfactant) or (amphoteric near3 surfactant) or (cationic near3 surfactant)) and (resin\$3 same (polyvinyl near3 (alcohol or acetal or acetate)) same cyclic same ((alkali\$3 or water) near2 solub\$5))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
2	142	((resist or photoresist) same (pattern\$4 or structure)) and (surfactant or (non\$3ionic near3 surfactant) or (amphoteric near3 surfactant) or (cationic near3 surfactant)) and (resin\$3 same (polyvinyl near3 (alcohol or acetal or acetate)) same ((alkali\$3 or water) near2 solub\$5)) and ((substrate or wafer) same (underly\$3 or coat\$3 or film) same (pattern\$3 or etch\$3 or RIE))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
3	11	((resist or photoresist) same (pattern\$4 or structure)) and (((non\$3ionic near3 surfactant) or (amphoteric near3 surfactant) or (cationic near3 surfactant)) same resin\$3 same (polyvinyl near3 (alcohol or acetal or acetate)) same ((alkali\$3 or water) near2 solub\$5)) and ((substrate or wafer) same (underly\$3 or coat\$3 or film) same (pattern\$3 or etch\$3 or RIE))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
4	1	("20030102285").PN.	USPAT; US-PGPUB

	Hits	Search Text	DBs
5	30	((resist or photoresist) same (pattern\$4 or structure) same \$3cyclic) and (surfactant or (non\$3ionic near3 surfactant) or (amphoterics near3 surfactant) or (cationic near3 surfactant)) and (resin\$3 same (polyvinyl near3 (alcohol or acetal or acetate)) same ((alkali\$3 or water) near2 solub\$5)) and ((substrate or wafer) same (underly\$3 or coat\$3 or film) same (pattern\$3 or etch\$3 or RIE))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB